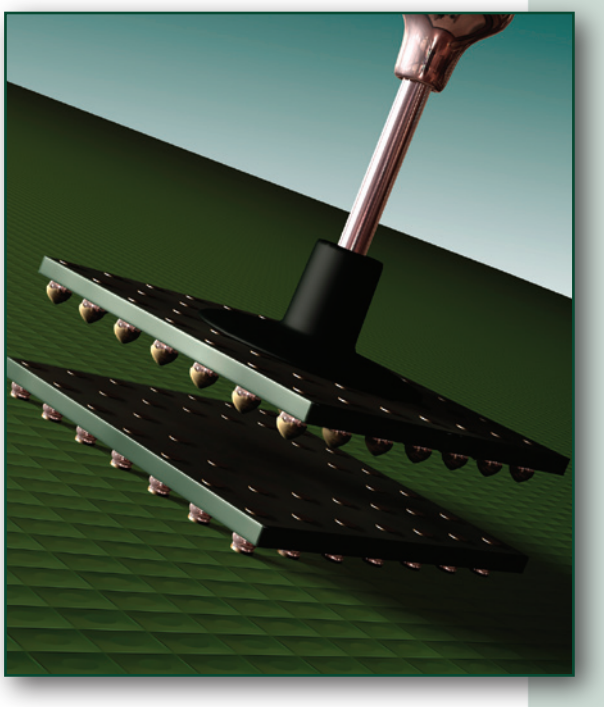
Package on Package (PoP) Flux 23LV

Features

- Rheology optimized for dipping and package-holding
- Holds packages up to 25mm x 25mm in outline
- Long pot life/working life
- Excellent solderability with Cu-OSP and Au/Ni finishes
- Optimized for Pb-Free (SAC alloy) applications
- Clear, non-brittle residue
- Air reflow



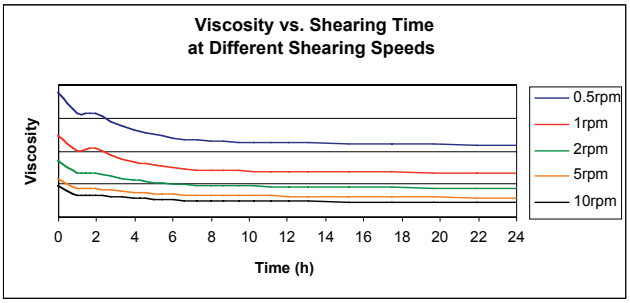
Introduction

PoP Flux 23LV is a thixotropic no-clean flux designed for package-on-package dipping applications with Pb-free solders. **PoP Flux 23LV** has a rheology designed to be sufficient to hold packages in place before and during reflow, yet allows the correct amount of flux to adhere to the spheres, over an extended pot-life.

Properties

	Value	Test Method
Flux type Classification:	ROL1	J-STD-004 (IPC-TM-650: 2.3.32 and 2.3.33)
Typical Viscosity:	250kcps	Brookfield RVT - TF Spindle (5rpm) J-STD-004 (IPC-TM-650)
SIR (ohms):	Pass (>10^9 after 7 days @ 85°C & 85% RH)	J-STD-004 (IPC-TM-650: 2.6.3.3 IPC-B-24)
Typical Acid Value:	102mg KOH/g	Titration
Typical Tack Strength:	240g	J-STD-005 (IPC-TM-650: 2.4.44)
Shelf Life:	12 months (0°C - 30°C)	Viscosity change/ microscope examination
Color:	Amber to light tan	Visual

All information is for reference only. Not to be used as incoming product specifications.



Application

The volume of flux on the package can be optimized by changing dipping-equipment parameters. Key variables include: sphere size, sphere pitch, flux shear speed, dwell, and depth of sphere immersion. Viscosity can be optimized per application by appropriate equipment setup.

Cleaning

PoP Flux 23LV is designed for no-clean applications, and can be left in place on the final package. If necessary, flux residues can be removed by using a commercially available flux cleaner.

Packaging

PoP Flux 23LV is available in air-free 30cc syringes or 100g jars. However other packaging can be provided to meet specific requirements.

OVER→

Form No. 98247 R3

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PoP Flux 23LV

Storage

For maximum shelf life, **PoP Flux 23LV** syringes and cartridges should be stored tip down. Storage temperatures should never exceed 30°C. After removing from cold storage, **PoP Flux 23LV** should be allowed to stand for at least 4 hours at room temperature before using.

Technical Support

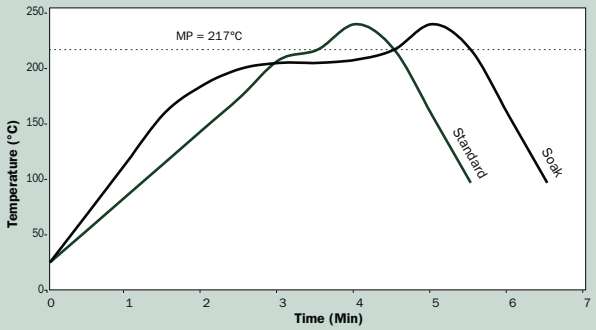
Indium Corporation sets the industry standard in providing rapid response, on-site technical support for our customers worldwide. Indium's team of Technical Support Engineers can provide expertise in all aspects of Materials Science and Semiconductor Packaging process applications.

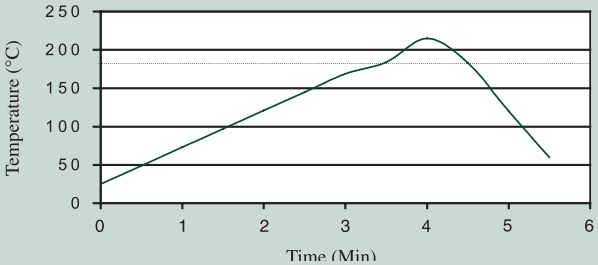
Material Safety Data Sheets

The MSDS for this product can be found online at http://www.indium.com/techlibrary/msds.php

Reflow

Recommended Profile:





Peak reflow temperature should be <350°C in an air or nitrogen atmosphere, with a linear ramp up to approximately 30°C above the solidus temperature

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices.

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